

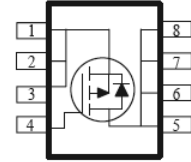
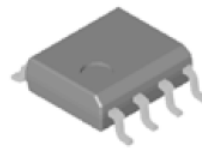


MS44P15 P-Channel MOSFET

FEATURES

These miniature surface mount MOSFETs utilize a high cell density trench process to provide low $r_{DS(on)}$ and to ensure minimal power loss and heat dissipation. Typical applications are DC-DC converters and power management in portable and battery-powered products such as computers, printers, PCMCIA cards, cellular and cordless telephones.

- Low $r_{DS(on)}$ provides higher efficiency and extends battery life
- Low thermal impedance copper lead frame SOIC-8 saves board space
- Fast switching speed
- High performance trench technology



V_{DS}	$R_{DS(ON)}$ (mohm)	I_D (A)
-20V	8.4 @ $V_{GS} = -4.5V$	-13.5
	10.4 @ $V_{GS} = -2.5V$	-12

RoHS
COMPLIANT

HALOGEN
FREE
Available

Absolute Maximum Ratings (Tc=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	VDS	-20	V
Gate-Source Voltage	VGS	±12	V
Continuous Drain Current @ TC=25°C	ID	-13.5	A
Pulsed Drain Current	IDM	±50	A
Continuous Source Current (Diode Conduction)	IS	-2.1	A
Operating Junction and Storage Temperature	Tj, Tstg	-55~+150	°C
Power Dissipation@ TC=25°C	PW	3.1	W

NOTE:

1. Repetitive rating; pulse width limited by maximum junction temperature.

Thermal characteristics (Tc=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Maximum Junction-to-Ambien	RθJA	50	°C/W
Maximum Junction-to-Case	RθJc	25	



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Characteristics (Tc=25°C, unless otherwise specified)

Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static Characteristics					
VGS	VGS = VDS, ID = 250 uA	-0.7	-	-	V
IGSS	VDS = 0 V, VGS = ± 12 V	-	-	±100	nA
IDSS	VDS = -16V, VGS = 0 V	-	-	-1.0	uA
	VDS = -16V, VGS = 0 V, Tj = 55oC	-	-	-5.0	uA
ID(on)	VDS = -4.5 V, VGS = 10 V	-50	-	-	A
RDS(on)	VGS = -4.5 V, ID = 13.5A	-	-	8.4	mΩ
	VGS = -2.5 V, ID = -12 A	-	-	10.2	mΩ
gfs	VDS = -15 V, ID = 11.5 A	-	70	-	S
VSD	IS = 2.5 A, VGS = 0 V	-	-0.6	-	V
Dynamic Characteristics					
Qg	VDS = -10V, VGS = -4.5V, ID = -13.5 A	-	66	-	nC
Qgs		-	13	-	nC
Qgd		-	17	-	nC
td(on)	VDD = -10V, RL = 6Ω, ID = -1A, VGEN = -4.5 V	-	20	-	nS
tr		-	23	-	nS
td(off)		-	289	-	nS
tf		-	134	-	nS

NOTE:

Pulse test: PW ≤ 300us duty cycle ≤ 2%.

Guaranteed by design, not subject to production testing.

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- Characteristic Curves

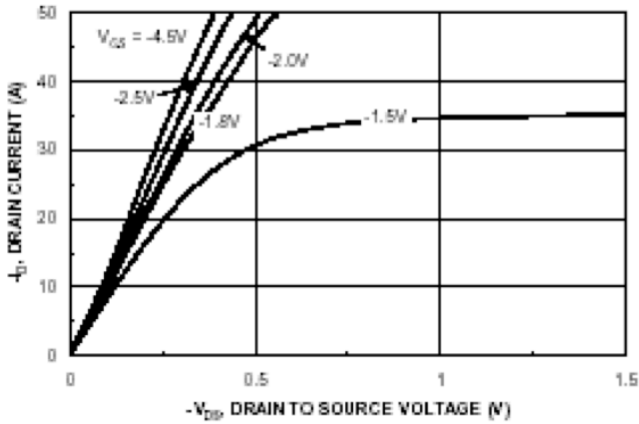


Figure 1. On-Region Characteristics

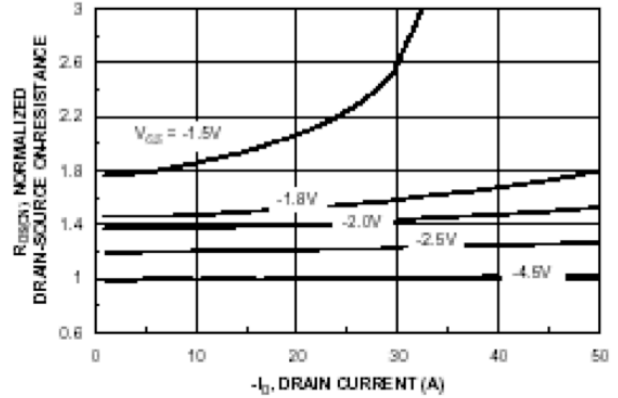


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage

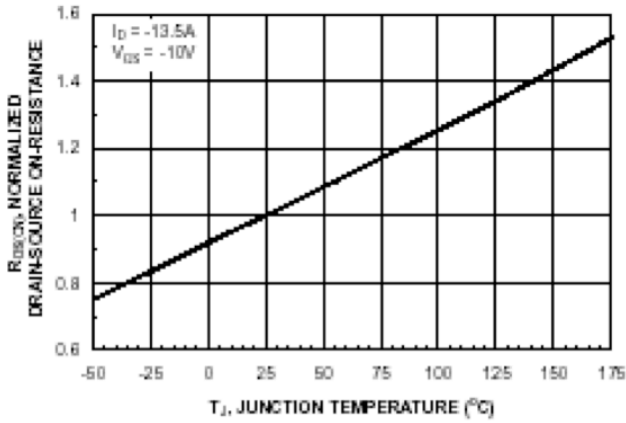


Figure 3. On-Resistance Variation with Temperature

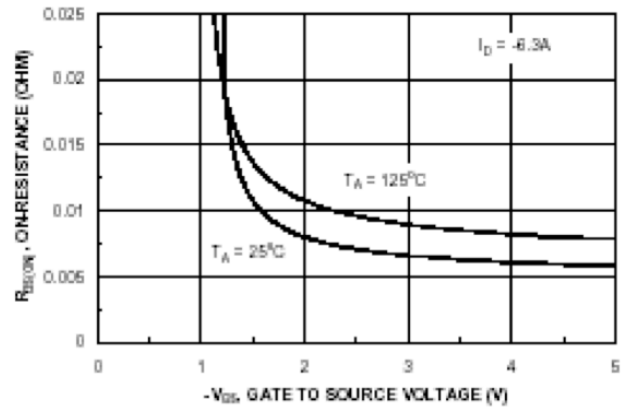


Figure 4. On-Resistance Variation with Gate to Source Voltage

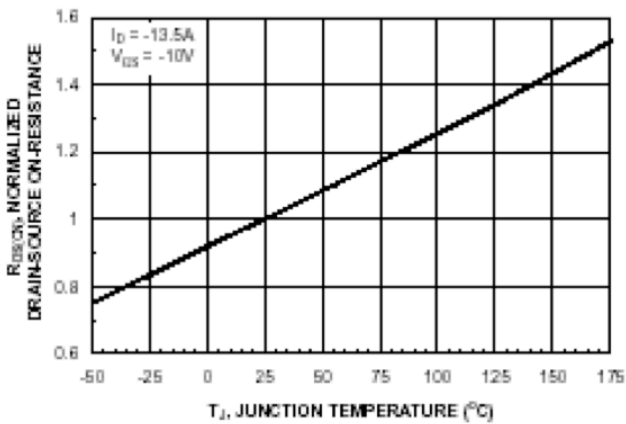


Figure 5. Transfer Characteristics

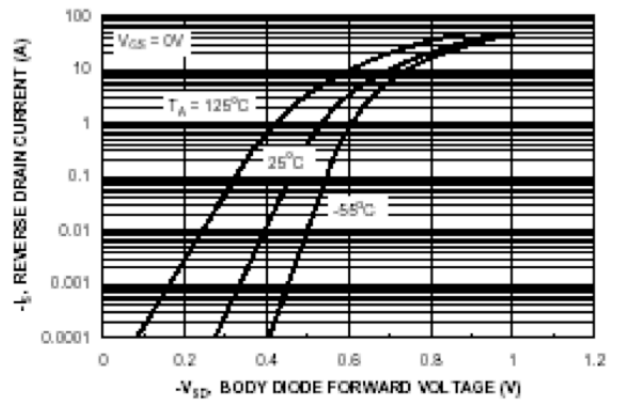


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature

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- Characteristic Curves

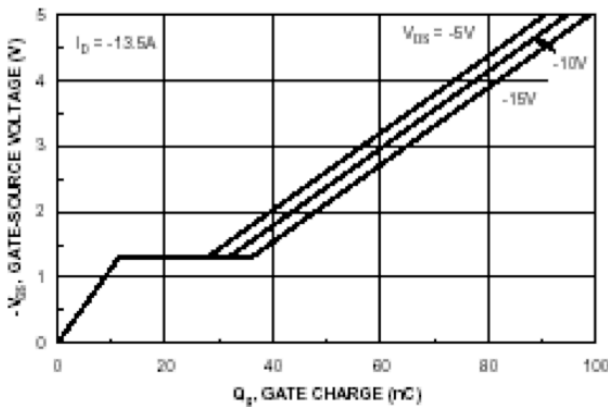


Figure 7. Gate Charge Characteristics

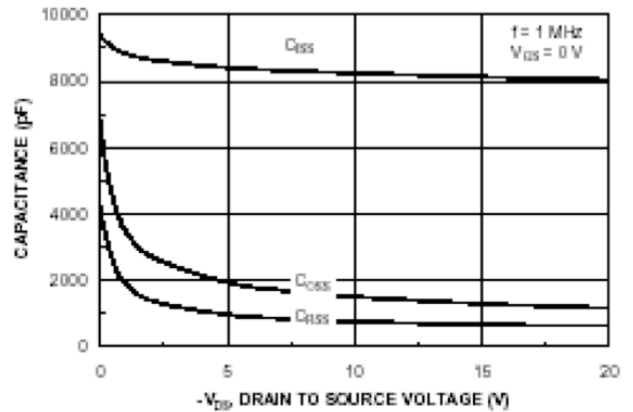


Figure 8. Capacitance Characteristics

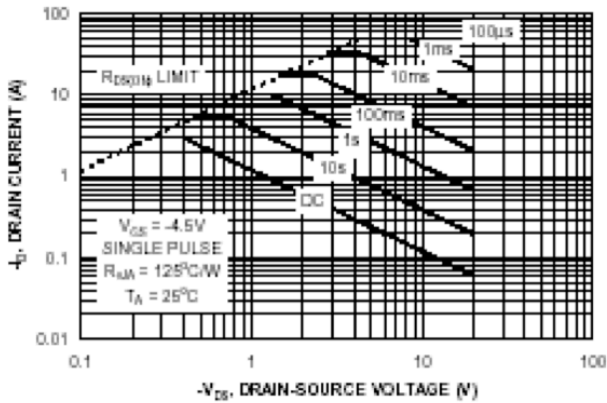


Figure 9. Maximum Safe Operating Area

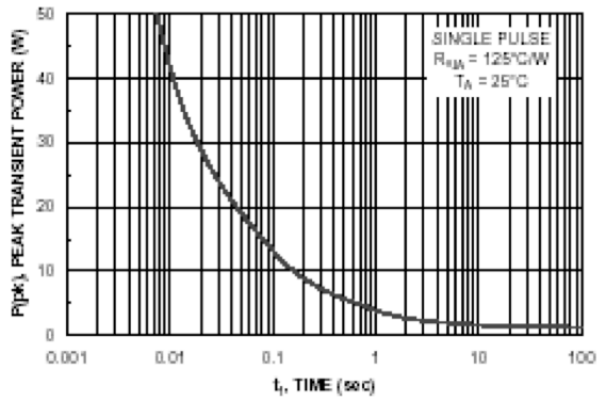


Figure 10. Single Pulse Maximum Power Dissipation

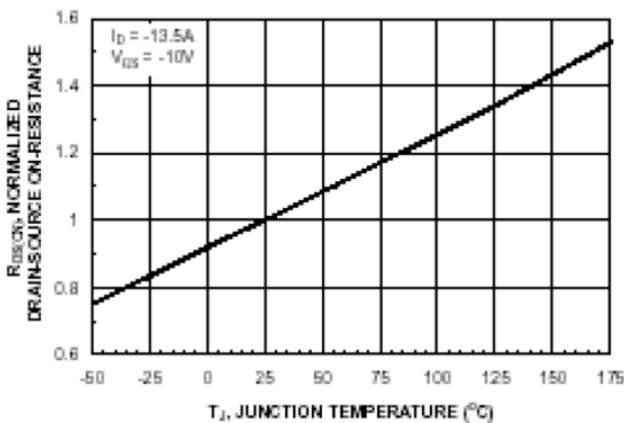


Figure 5. Transfer Characteristics

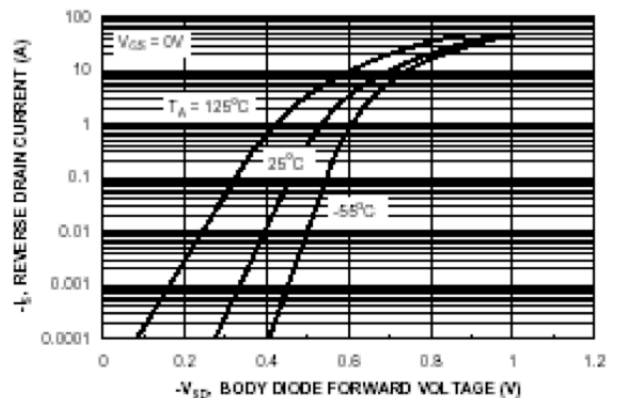


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature

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Normalized Thermal Transient Junction to Ambient

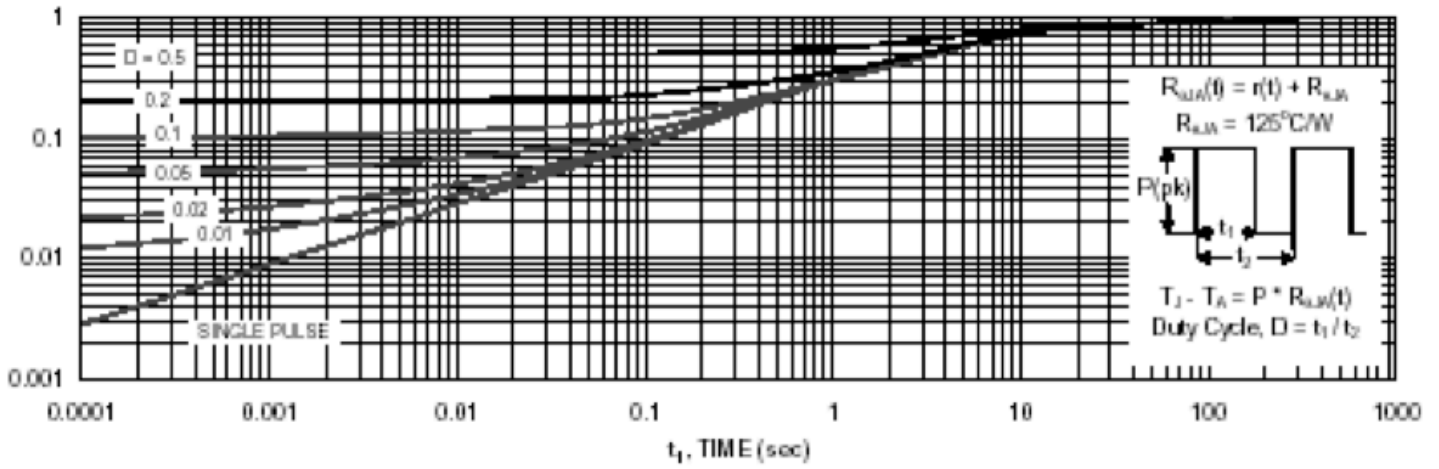


Figure 11. Transient Thermal Response Curve